

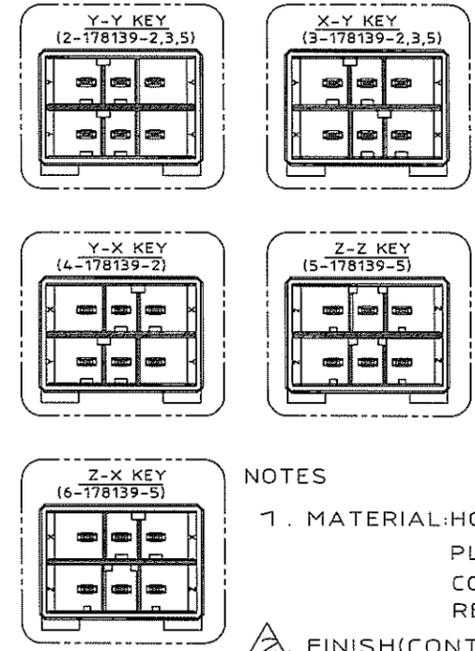
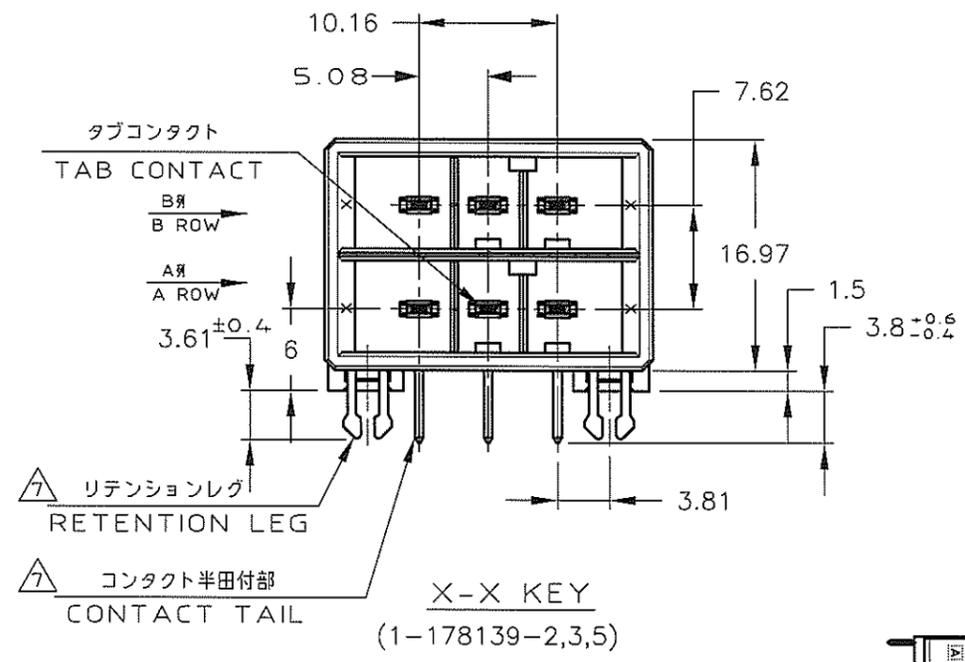
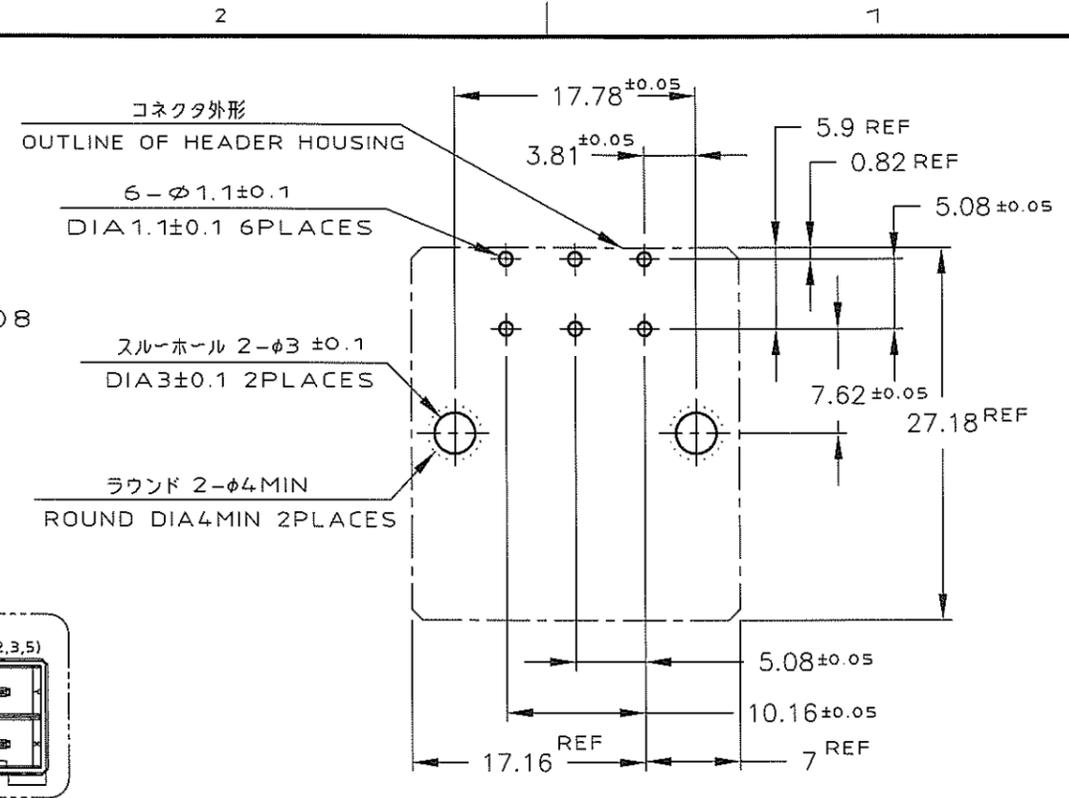
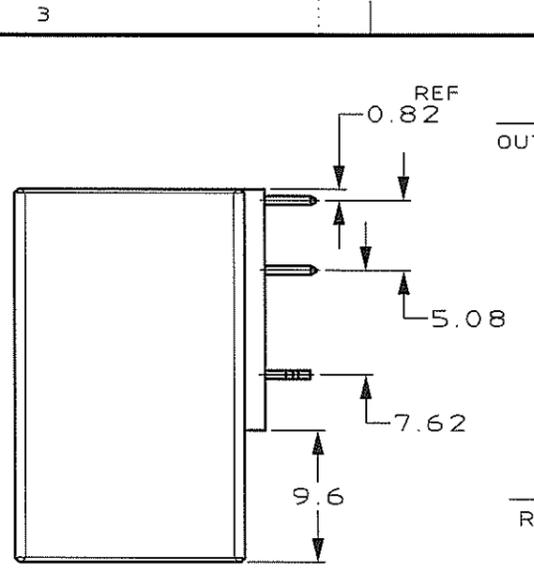
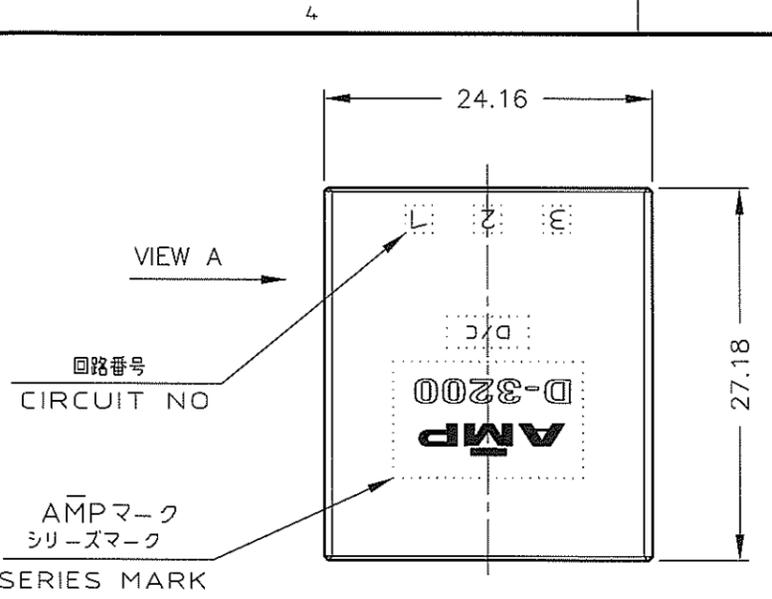
NUMBER 178139

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



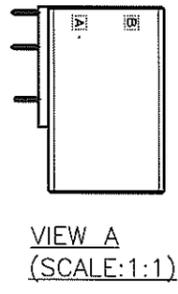
- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - PRODUCT SPEC: 108-5349
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
 - めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき
 - 製品規格: 108-5349
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき

7	4	1,2,3,5,6-178139-5
7	3	1,2,3-178139-3
7	2	1,2,3,4-178139-2
(FINISH)		製品番号 (PART NO.)



				WIRE RANGE		INSULATION DIA		NAME					
				mm ² (AWG -)		mmφ		6 POS SINGLE ROW					
				MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200					
				DR. 20/MAR/95 K.IKEDA		DE. 20/MAR/95 K.IKEDA		一般公差 (GENERAL TOLERANCE)		SIZE	LOC	NUMBER	
				CHK. 23/MAR/95 S.MANABE		APP. 23/MAR/95 S.MANABE		10% ±0.3 30% ±0.4 100% ±0.45 公差 ±3'		A3	J	C-178139	
E3 REVISED PER ECO-11-005030				RK	HMR	14APR 11		SCALE		REV.		SHEET	
LTR REVISION RECORD				DR	CHK	DATE		2-1		E3		1 OF 1	

Mouser Electronics

Authorized Distributor

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[TE Connectivity:](#)

[2-178139-3](#)